



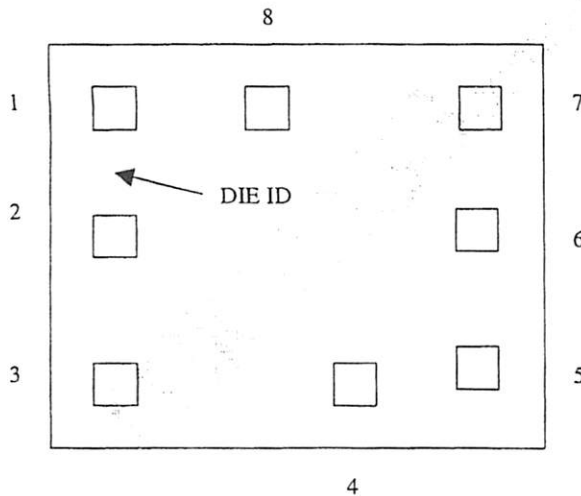
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

PAD FUNCTIONS

1. 1A
2. Vcc
3. 1Y
4. 2B
5. 2A
6. GND
7. 2Y
8. 1B



Top Material: Al
Backside Material: Silicon Nitride
Bond Pad Size: .004" X .004"
Backside Potential: Grnd (Or Leave Floating)
Mask Ref:

APPROVED BY: DK

DIE SIZE .029" X .031"

DATE: 3/30/12

MFG: Texas Inst.

THICKNESS .025"

P/N: 54LVC2G86